Application Form for IC Innovation Acceleration Soft-landing Resource Requirement

Explanation of the Guidelines:

IC Innovation Acceleration Soft-landing leverages Taiwan's leading semiconductor capabilities and abundant resources to consolidate key resources needed for chip development, assisting global IC startups in accelerating the realization of potential products.

Detailed required support: (Please describe the product and required support in detail, including product specifications, process nodes, collaboration need with Taiwanese manufacturers, etc.)

☐ Product name and functions diagram:

☐ Product specifications: (please list details)

Resource requirements for product development: (multiple answers and description accepted)

☐ EDA tools requirements:

☐ IP requirements:

☐ Requirements of IC design service:

☐ Target of foundry:

☐ IC Process node: ____ nm

☐ Process Type (GP, BCD, RF, Mixed-Signal…etc.) ：

____

☐ Special requirements for packaging and testing:

☐ System integration or EVB requirements:

☐ Equipment Manufacturer:

☐ Product schedule:

☐ Have you contacted any suppliers from Taiwan? If so, please list them.

Other requirements:

☐ Business development requirements:

☐ Fundraising requirements:

☐ Company registration in Taiwan:

☐ Others (please elaborate additional product development requirements, etc.)

Equity Information

Equity structure:

Shareholder name	Nationality	Ratio

Signature of consent (signature of the company representative or CEO. For teams, all team members need to sign):

____